

Material #	CPDH3 SERIES	
Product Line	SOT-523 Series	
Date	2009/4/21	
Rev. date	B	

COMPONENT DETILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Lead Frame	Substrate/Terminal	1.14	Copper	7440-50-8	> 97%	40.70%	
				Iron	7439-89-6	2.1%~2.6%		
				Zinc	7440-66-6	0.05%~0.2%		
				Phosphorus	7723-14-0	0.015%~0.15%		
				Lead	7439-92-1	<0.03%		
				Silver	7740-22-4	Surface Plating		
2	Wire	Conductor	0.019	Aurum	7440-57-5	100.00%	0.68%	
3	Mold Compound	Outer	1.3	Silica Fused	60676-86-0	78%~85%	46.41%	
				Epoxy resin	29690-82-2	5%~12%		
				Phenolic Resin	9003-35-4	3%~8%		
				Brominated Resin	N/A	1%~2%		
				Carbon Black	1333-86-4	0.1%~1%		
				Wax	N/A	0.5%~2%		
				Flame Retardant	N/A	1%~5%		
				Catalyst	N/A	<1%		
				Stress Absorbent	N/A	<5%		
				Coupling Agent	N/A	<1%		
4	Wafer	Diode	0.200	Silicon	N/A	95.49%	7.14%	
				Gold	N/A	3.50%		
				Aluminum	N/A	1.00%		
				Impurity	N/A	0.01%		
5	Plating	Protector	0.142	Tin	7440-31-5	100.00%	5.07%	
Total weight			2.801					